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FIG. 1A

resist application, baking or the like

FIG. 1B

exposing common part by first exposure means
(mirror projection exposure,
step and repeat exposure,
step and scan exposure or the like)

FIG. 1C

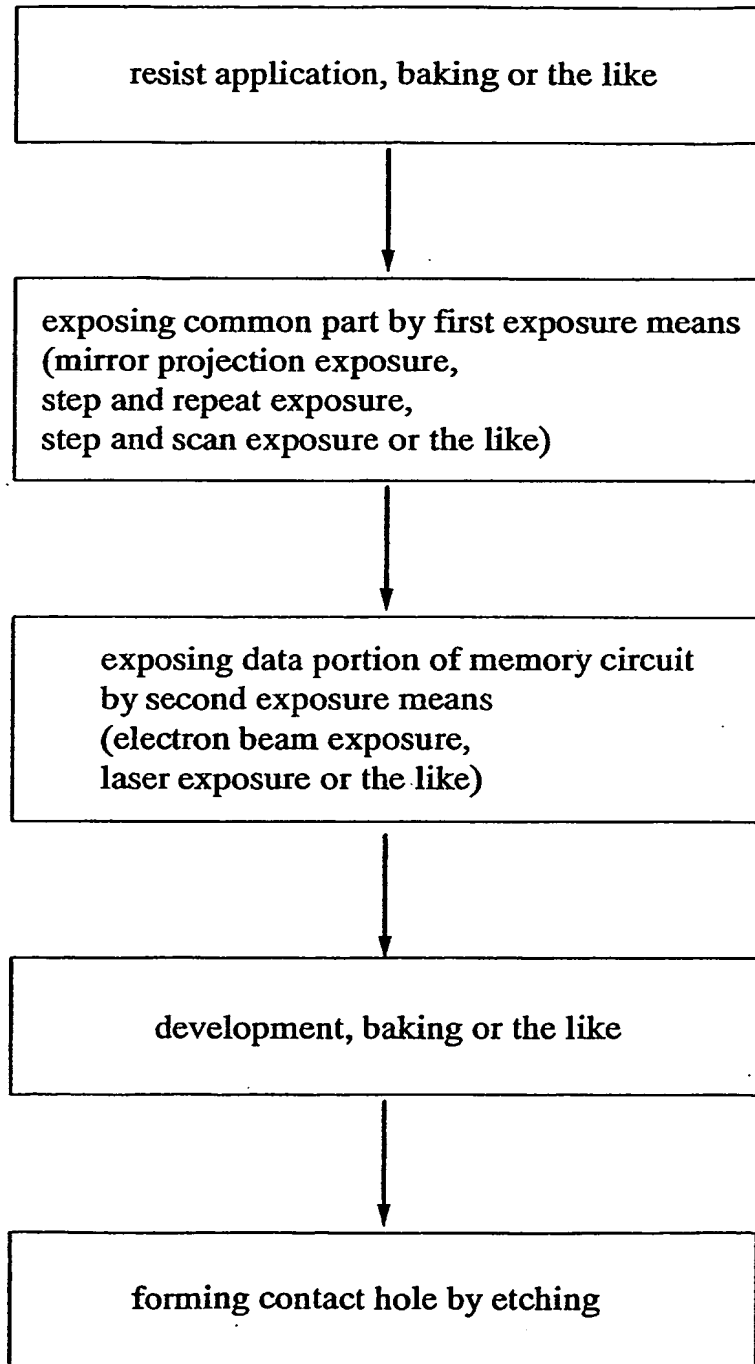
exposing data portion of memory circuit
by second exposure means
(electron beam exposure,
laser exposure or the like)

FIG. 1D

development, baking or the like

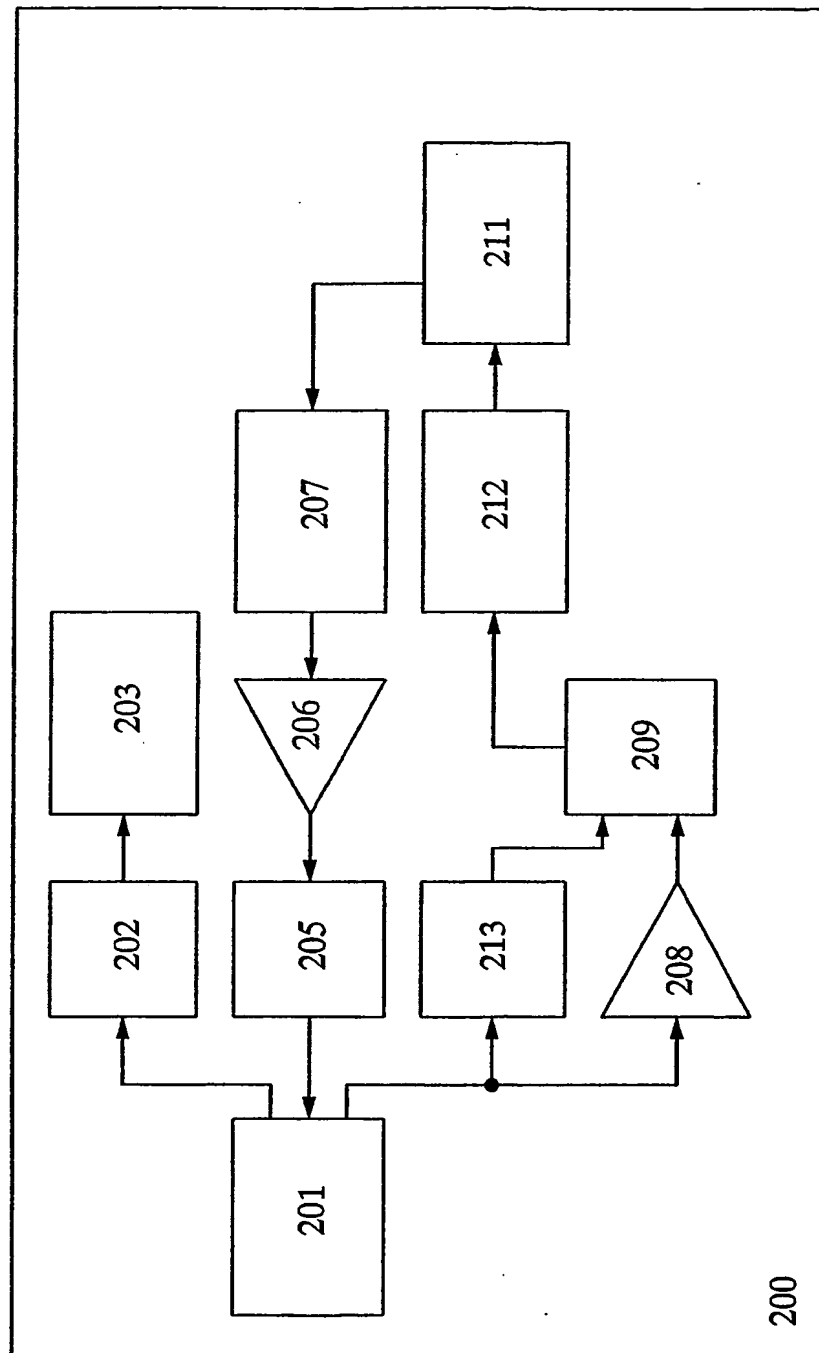
FIG. 1E

forming contact hole by etching



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FIG. 2



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FIG. 3A

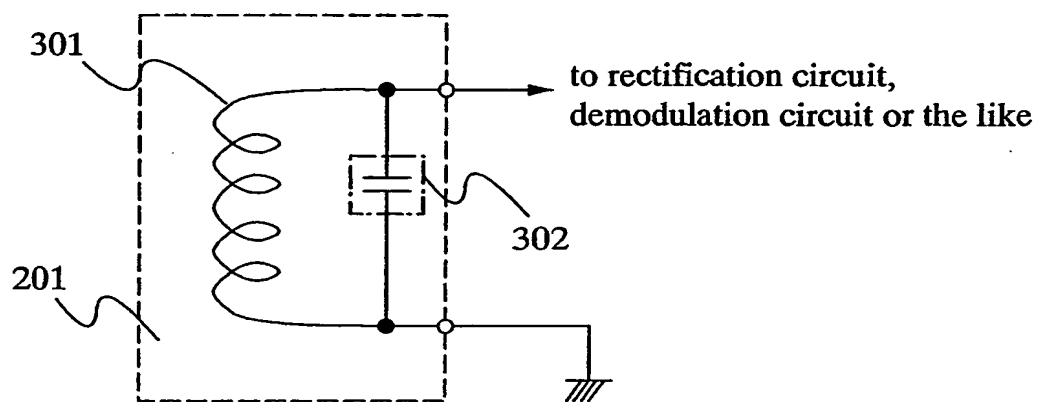
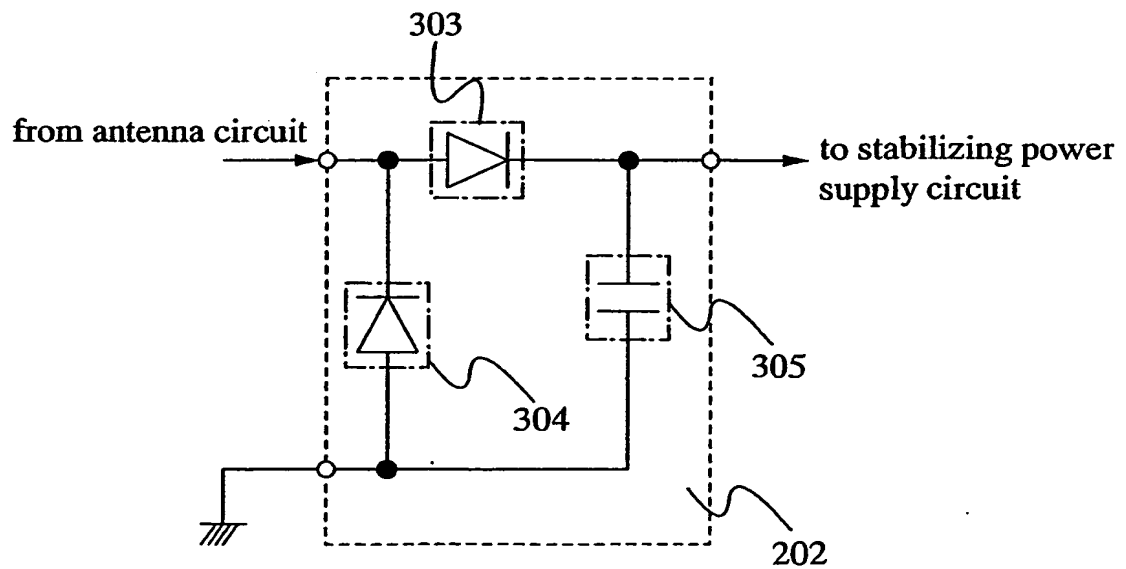
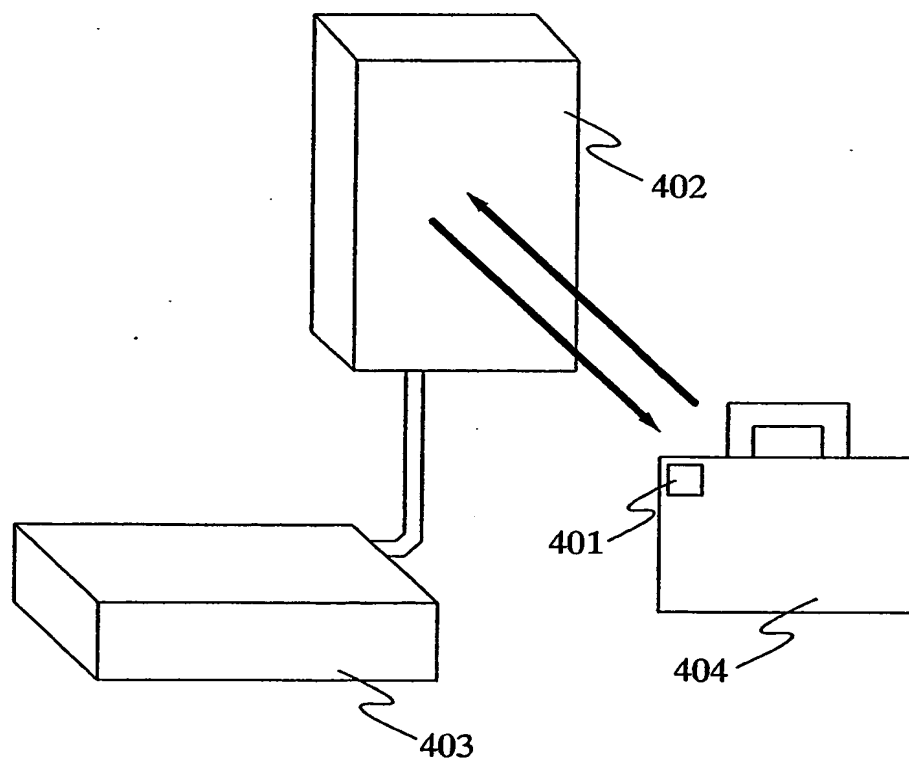


FIG. 3B



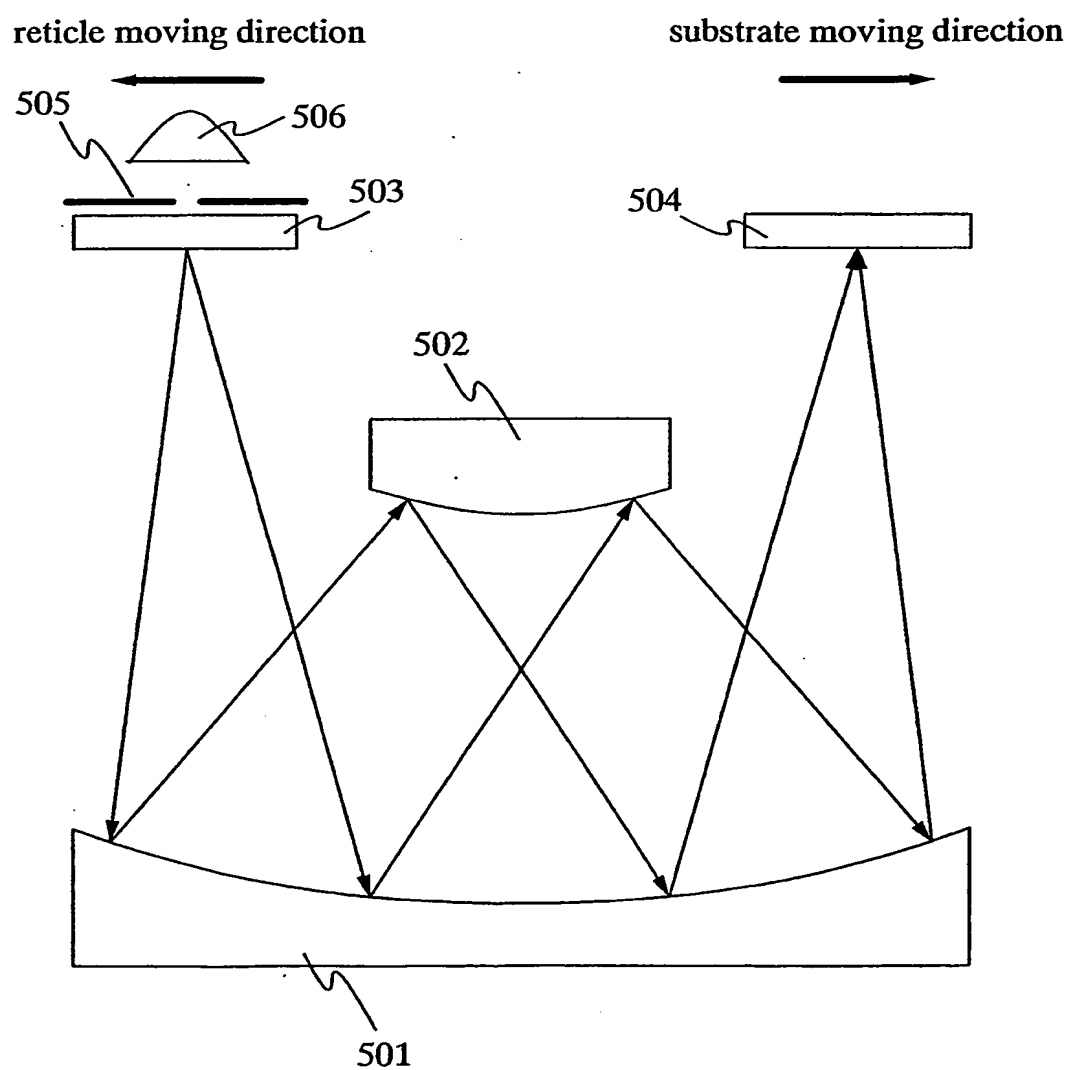
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FIG. 4



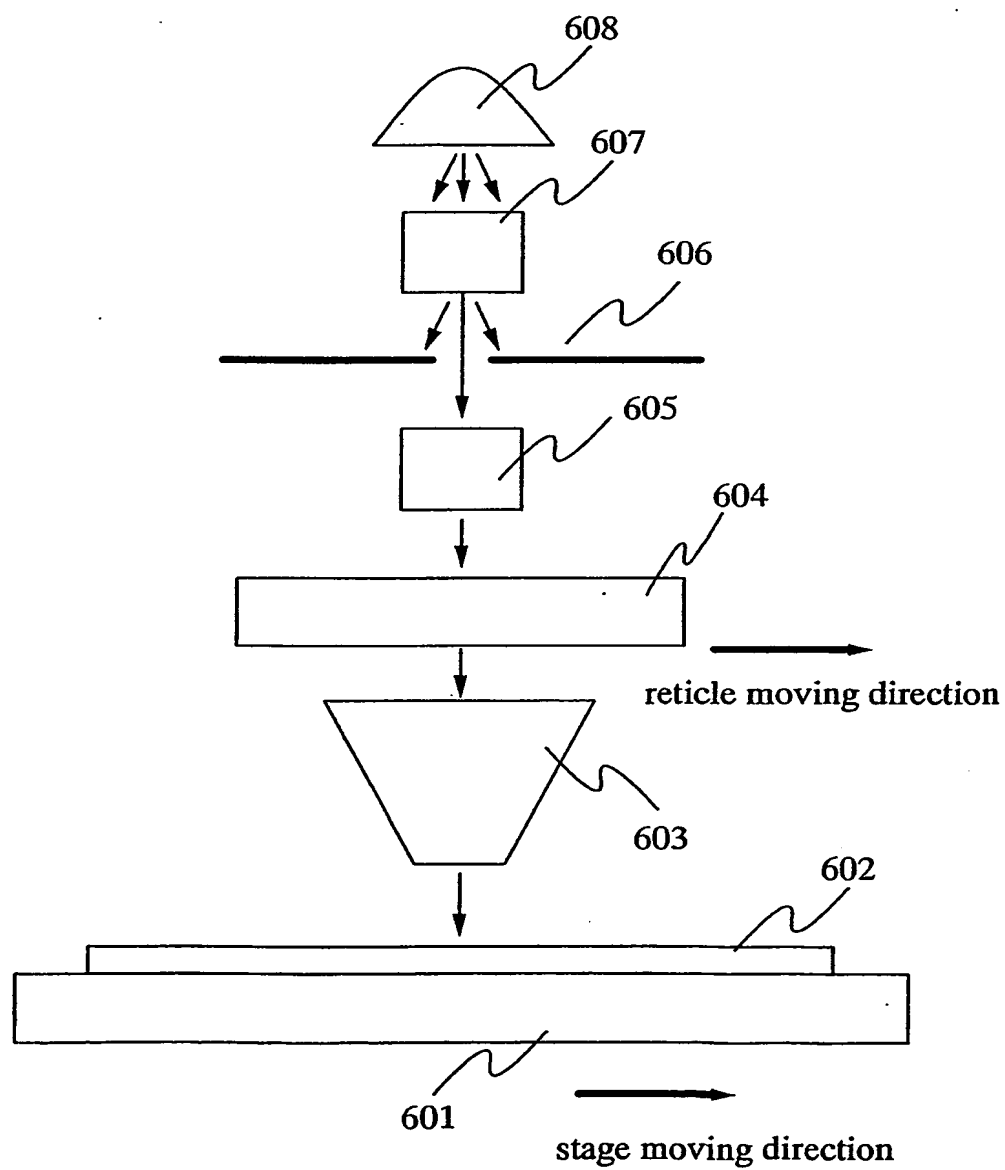
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FIG. 5

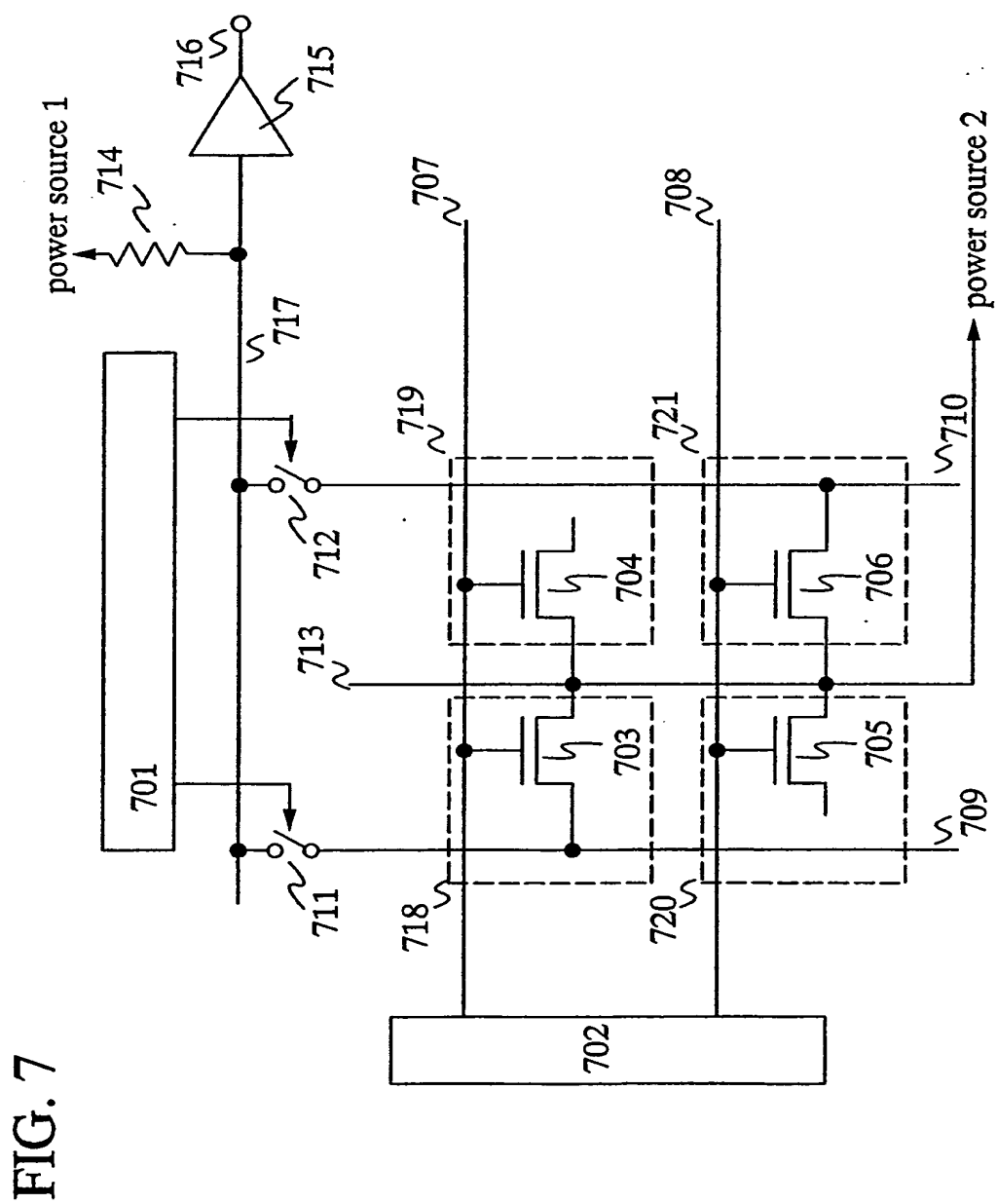


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FIG. 6

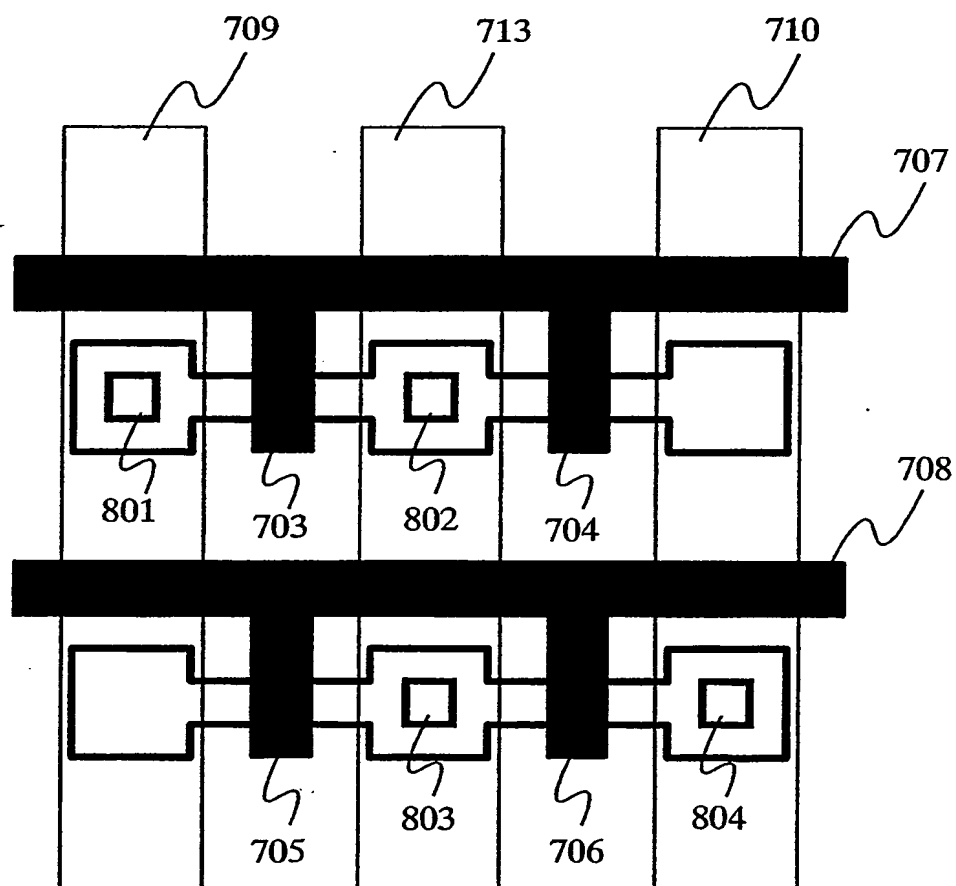


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FIG. 8



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FIG. 9A

resist application, baking or the like

FIG. 9B

exposing common part by first exposure means
(mirror projection exposure,
step and repeat exposure,
step and scan exposure or the like)

FIG. 9C

development, baking or the like

FIG. 9D

forming common part by etching

FIG. 9E

resist application, baking or the like

FIG. 9F

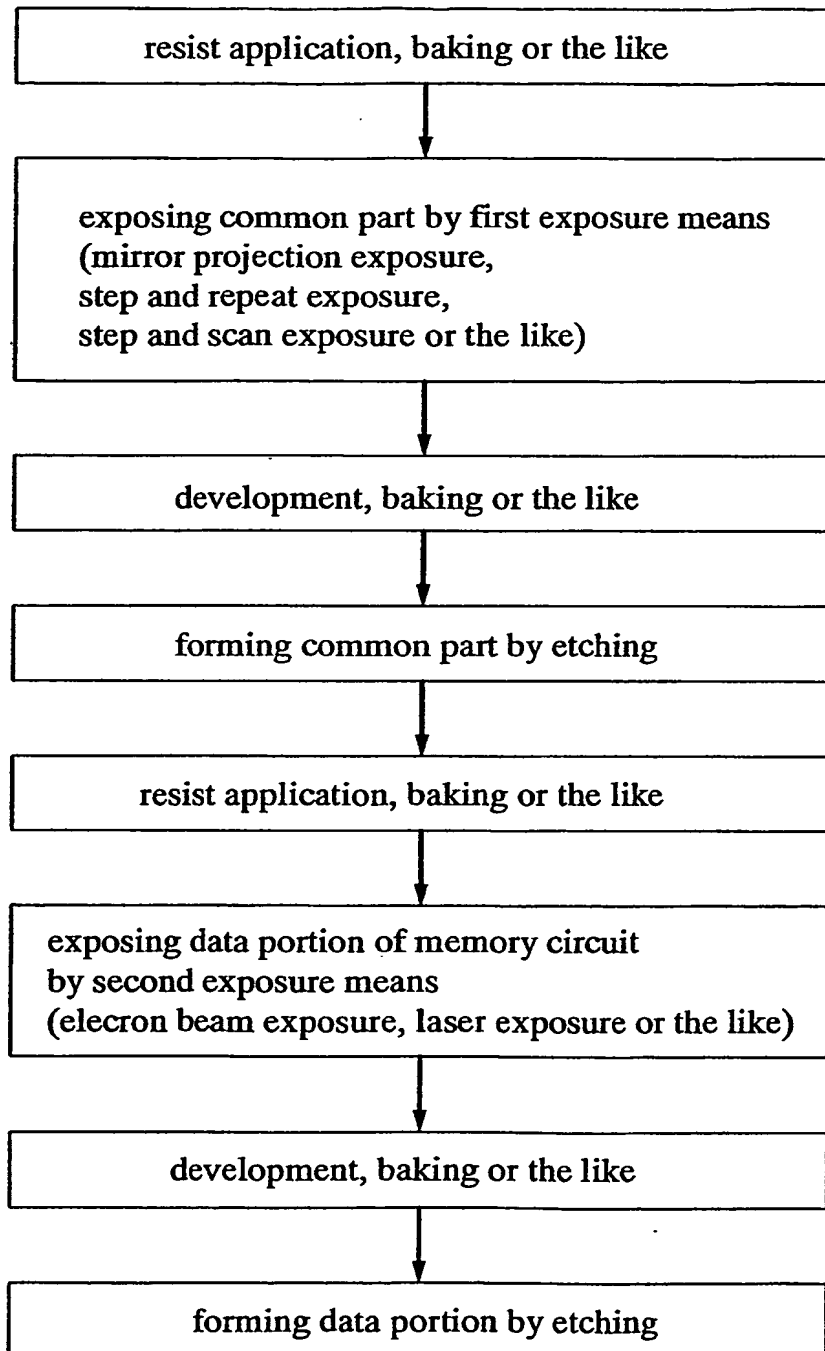
exposing data portion of memory circuit
by second exposure means
(electron beam exposure, laser exposure or the like)

FIG. 9G

development, baking or the like

FIG. 9H

forming data portion by etching



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FIG. 10A

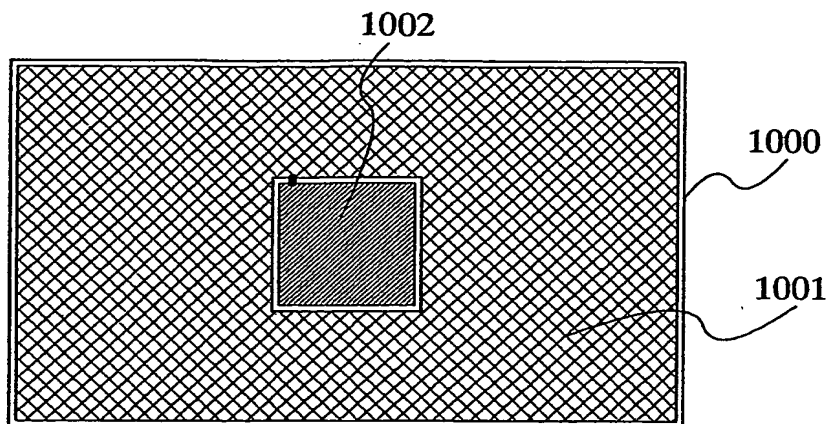


FIG. 10B

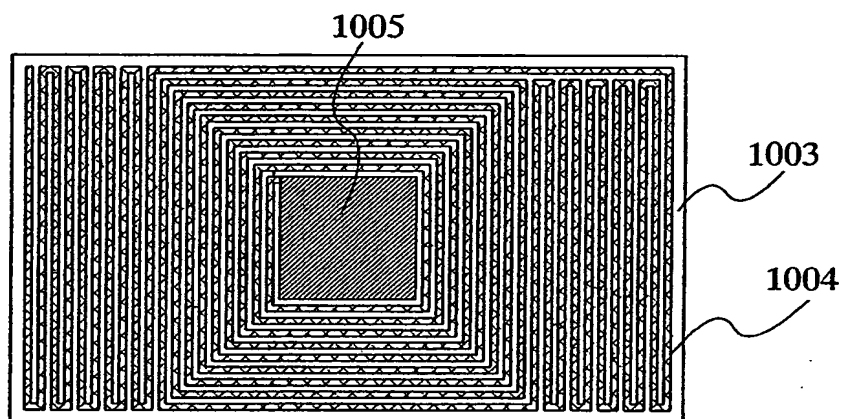


FIG. 10C

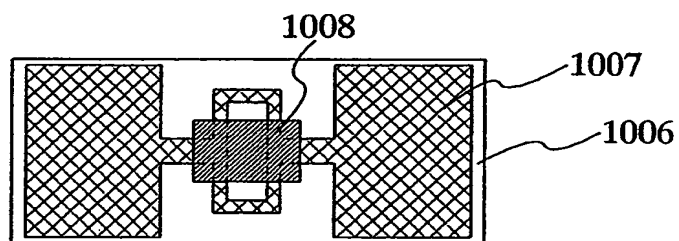


FIG. 10D

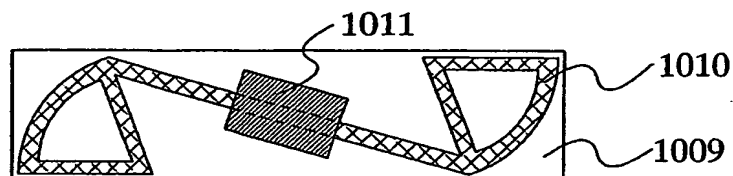
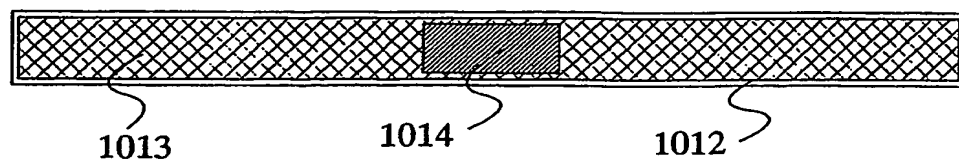


FIG. 10E



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FIG. 11A

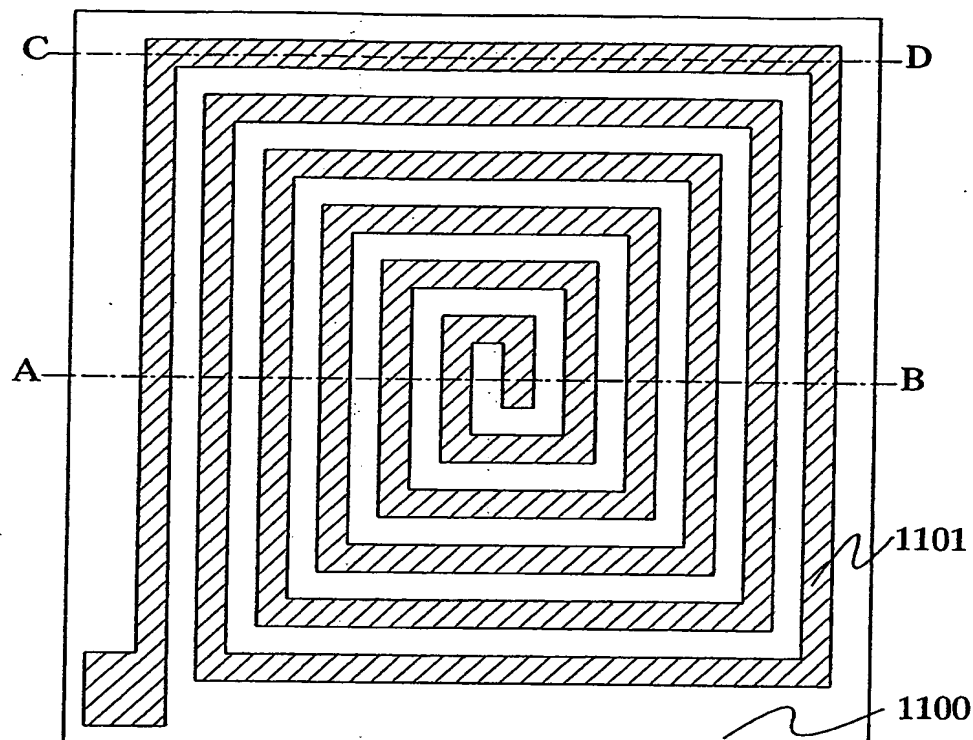


FIG. 11B

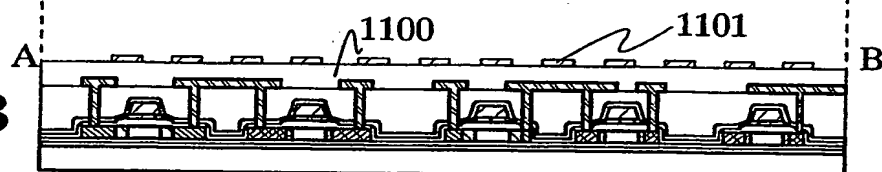
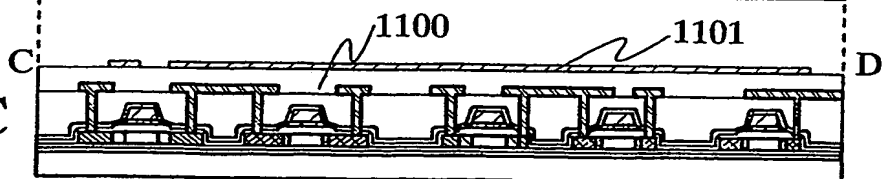
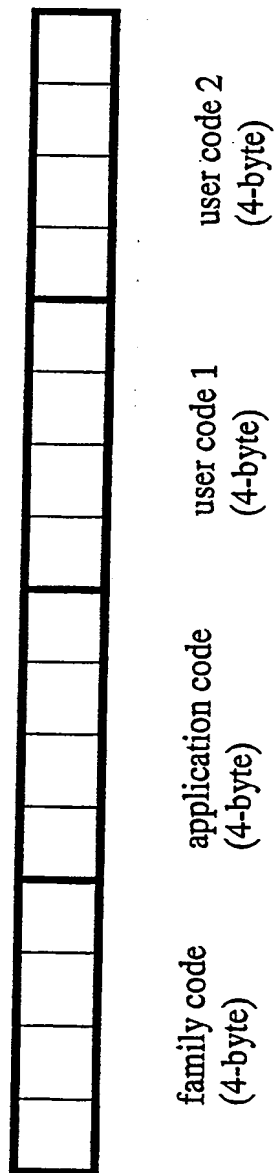


FIG. 11C



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FIG. 12



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FIG. 13

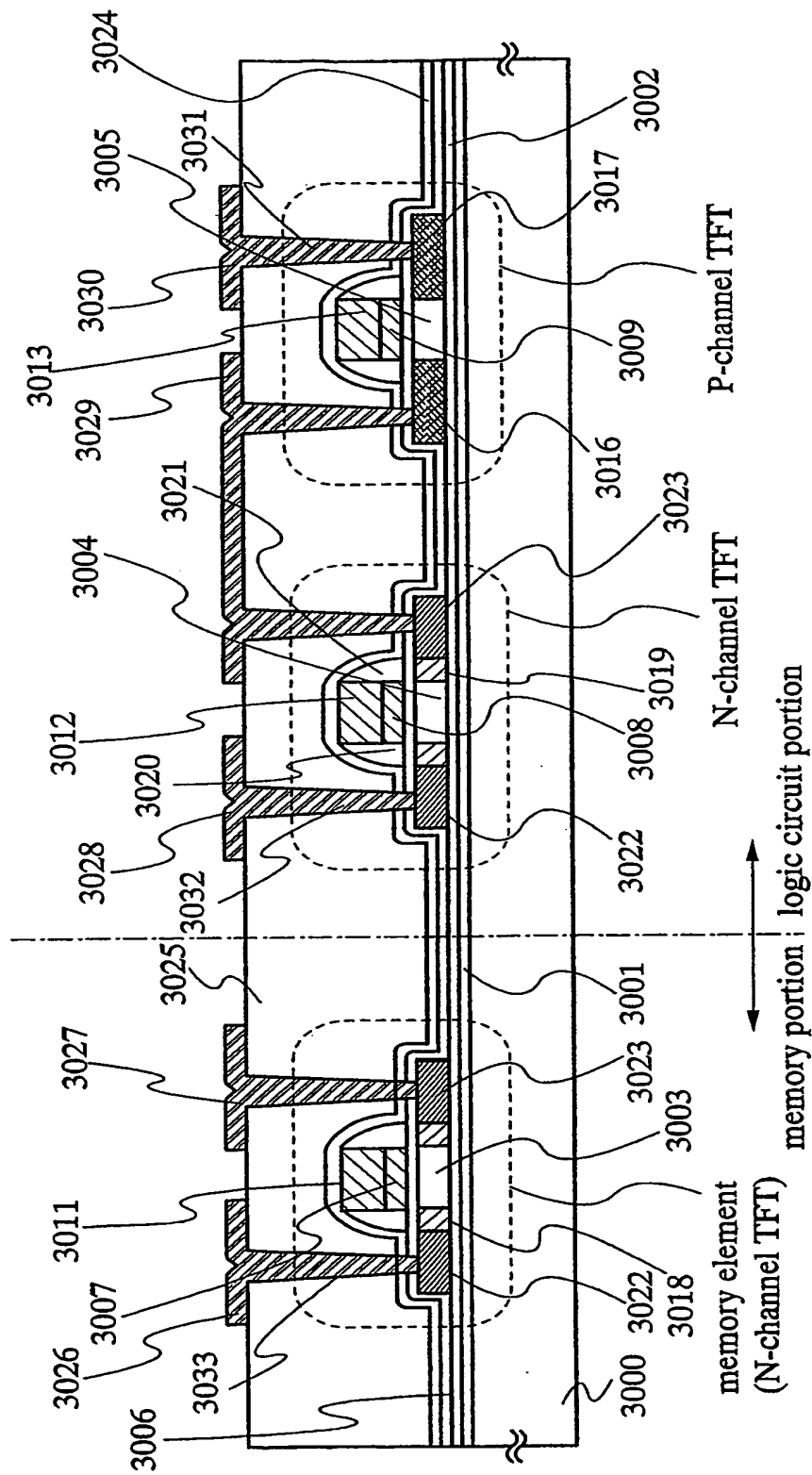


FIG. 14A

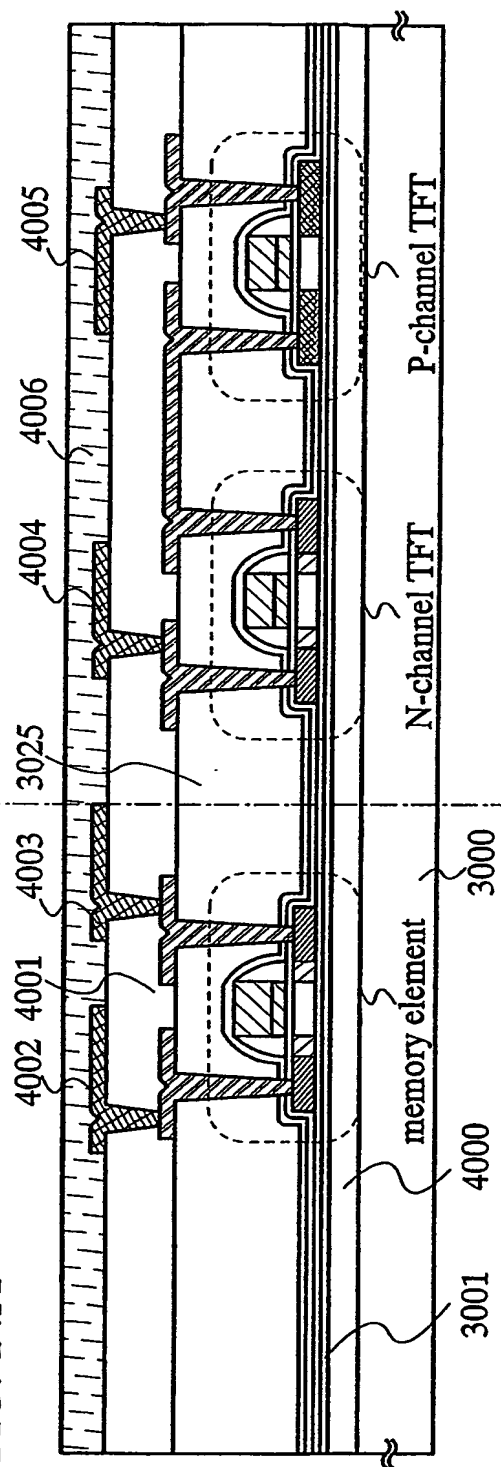


FIG. 14B

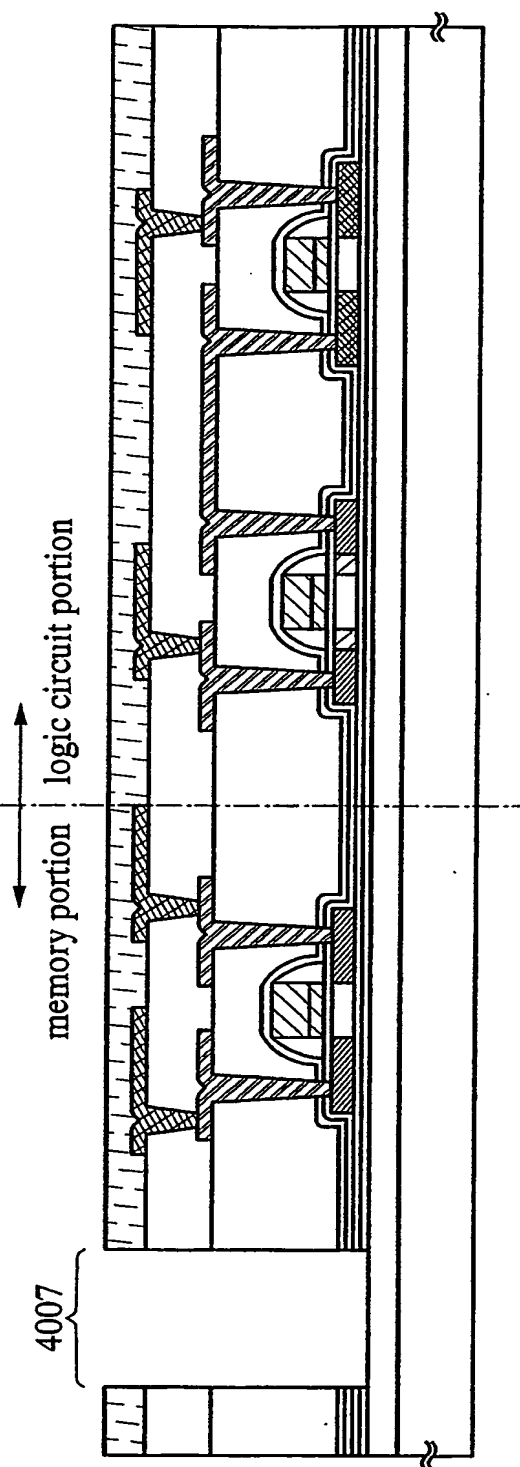


FIG. 15A

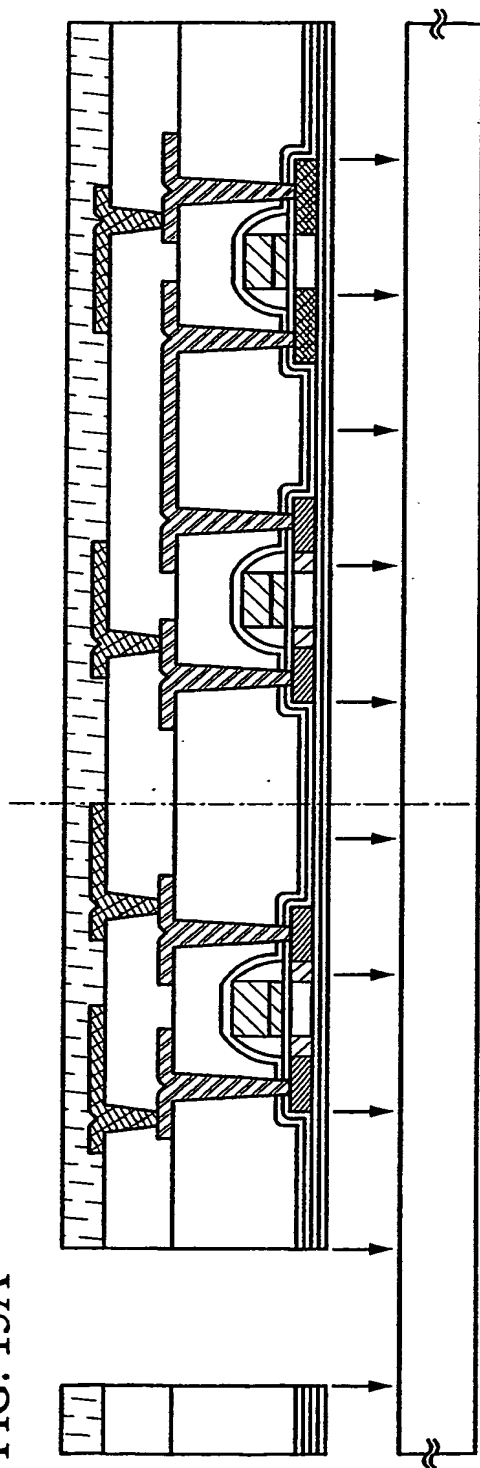
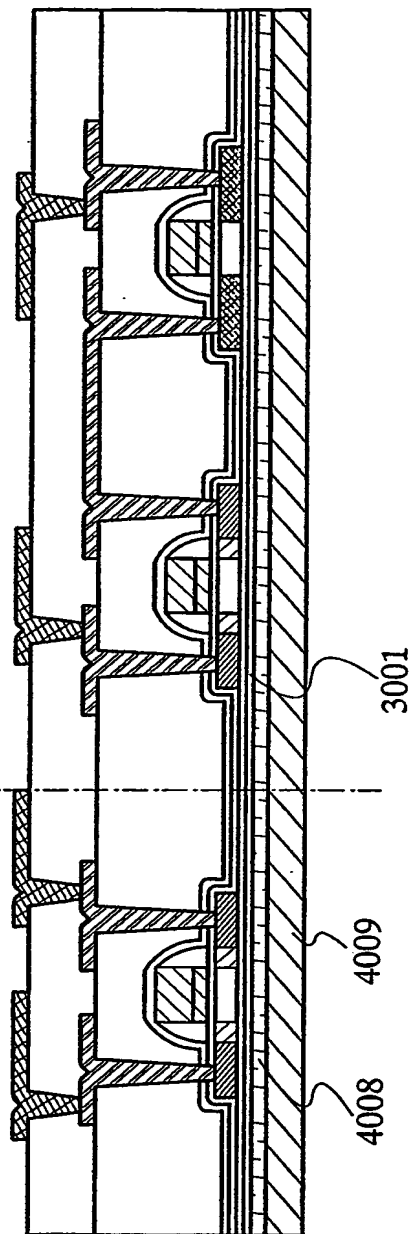


FIG. 15B



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FIG. 16A

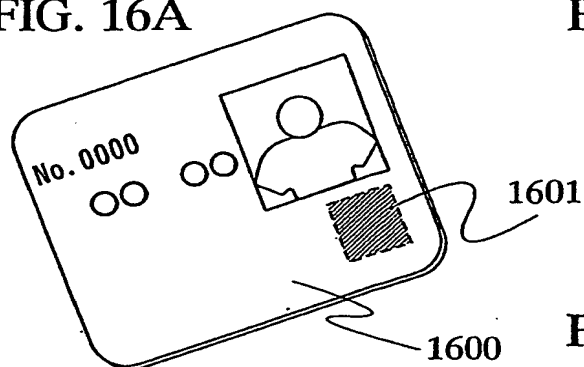


FIG. 16B

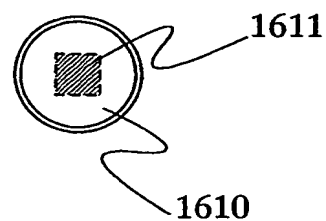


FIG. 16C

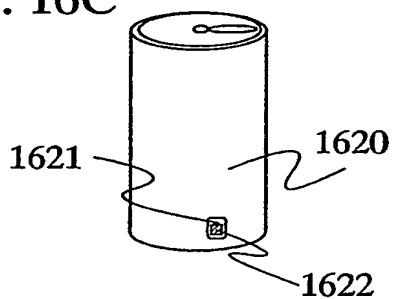


FIG. 16D

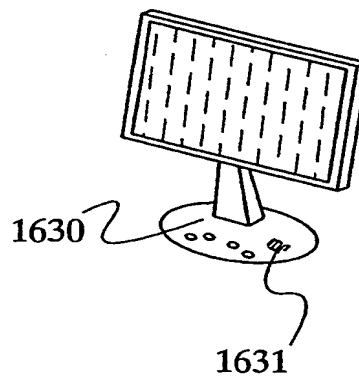


FIG. 16E

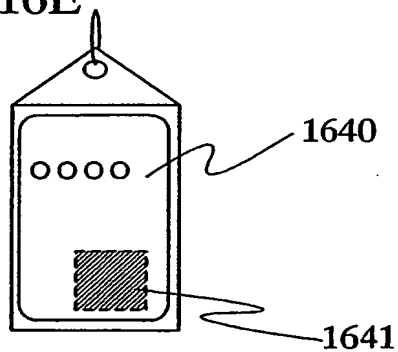


FIG. 16F

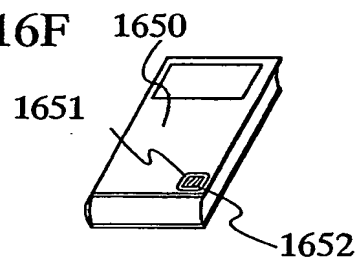


FIG. 16G

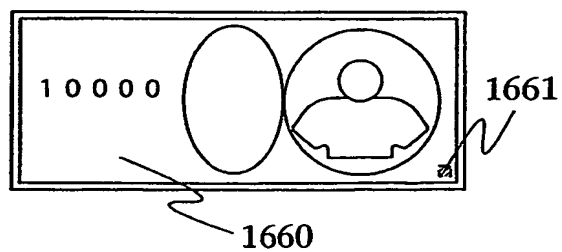
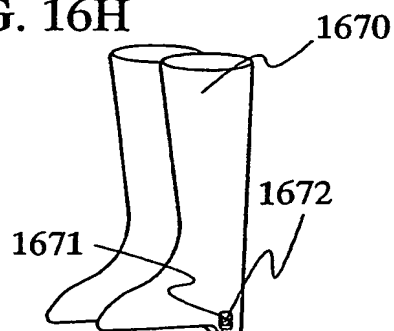
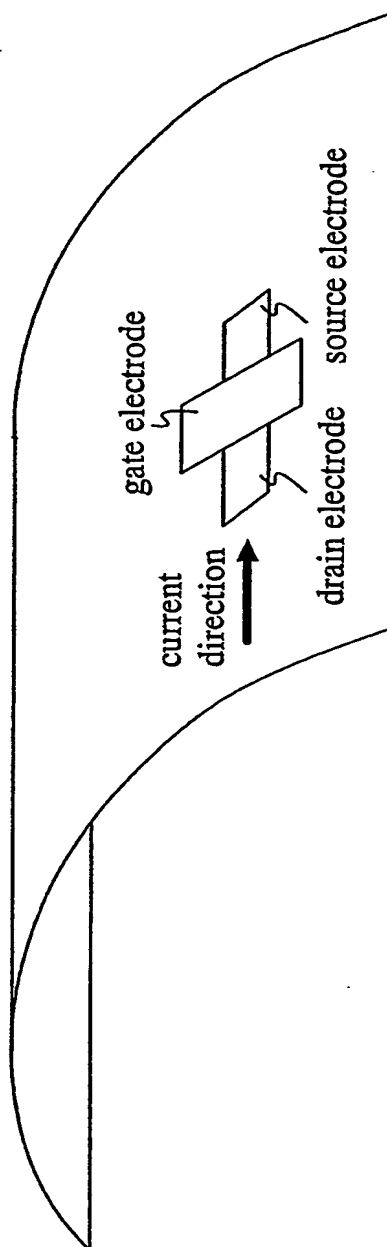


FIG. 16H



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FIG. 17



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FIG. 18A

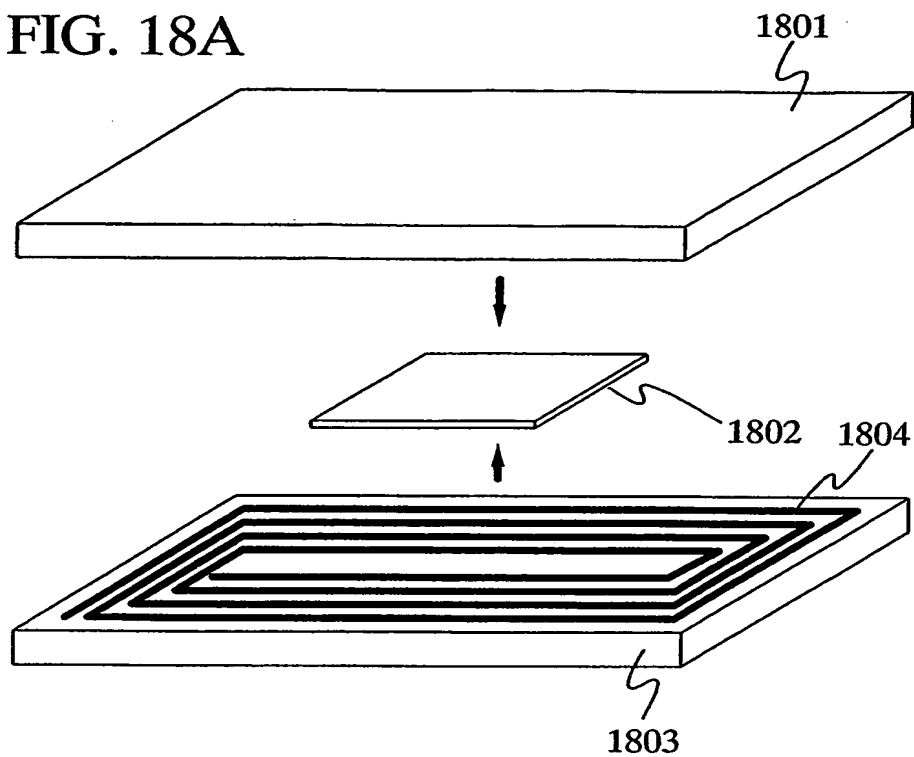
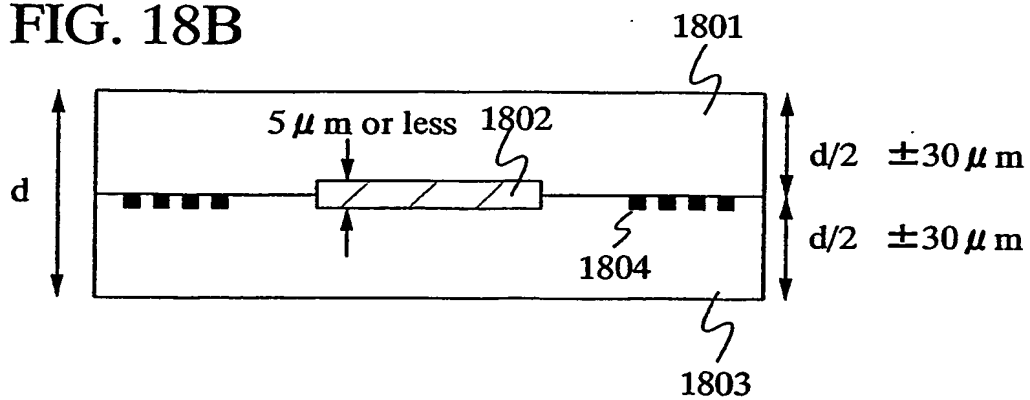
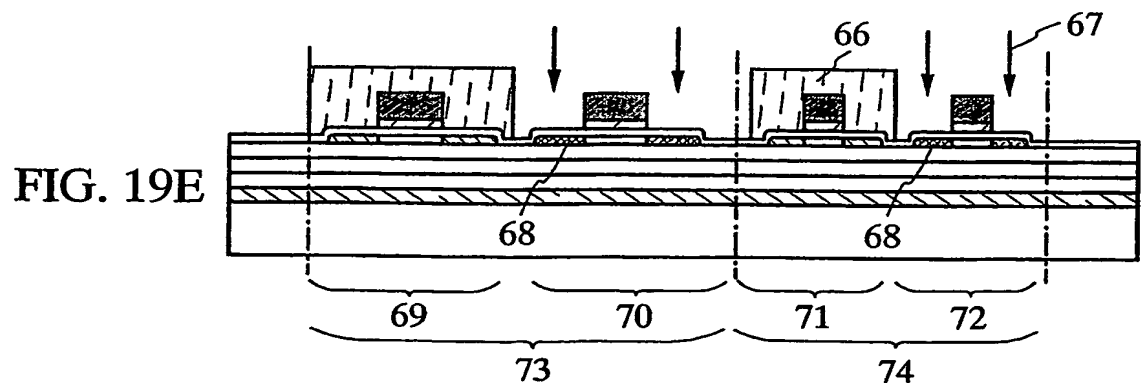
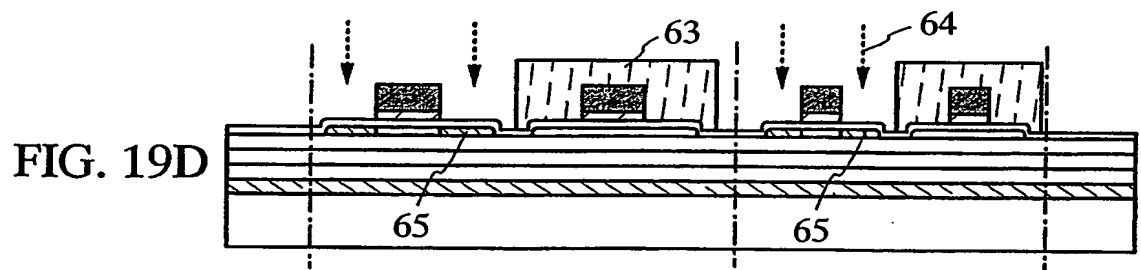
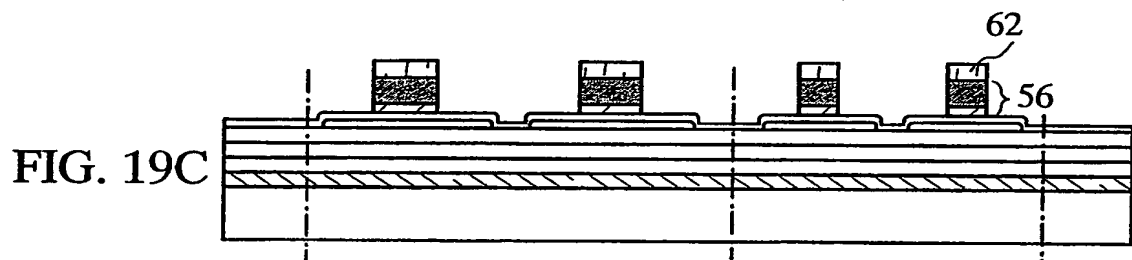
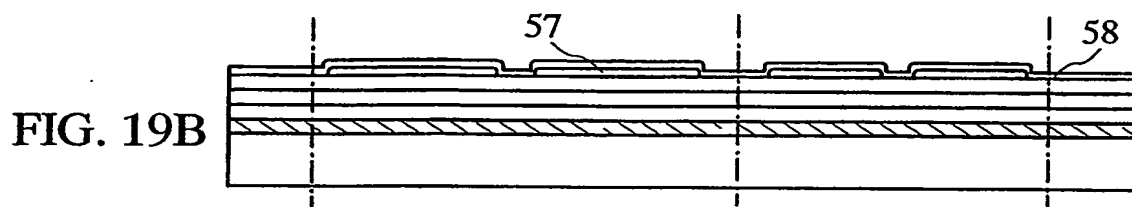
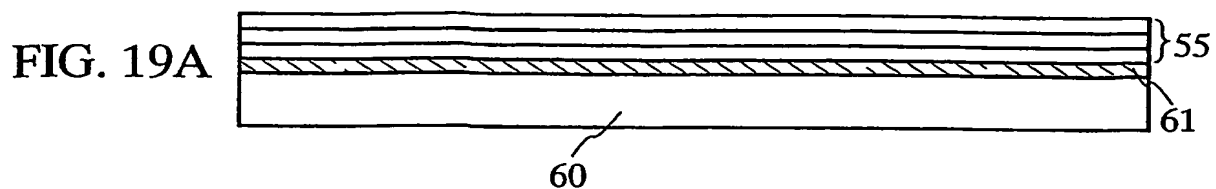


FIG. 18B



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FIG. 20A

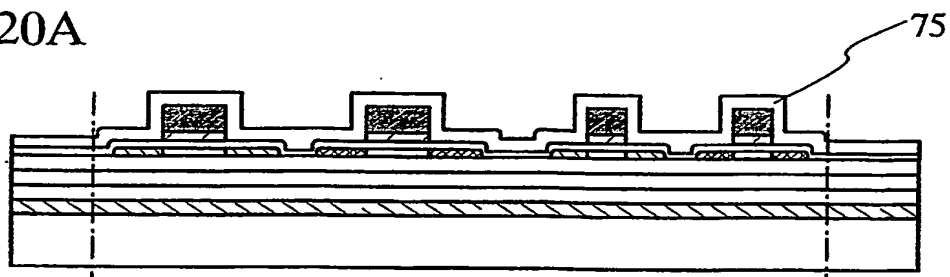


FIG. 20B

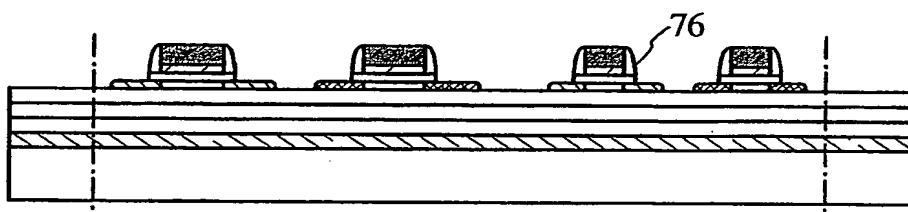


FIG. 20C

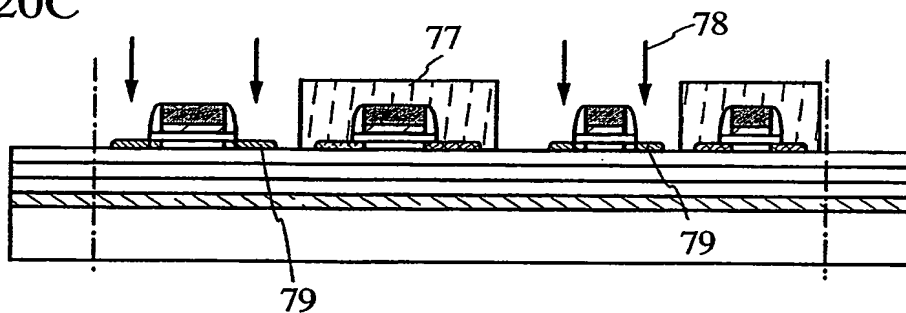
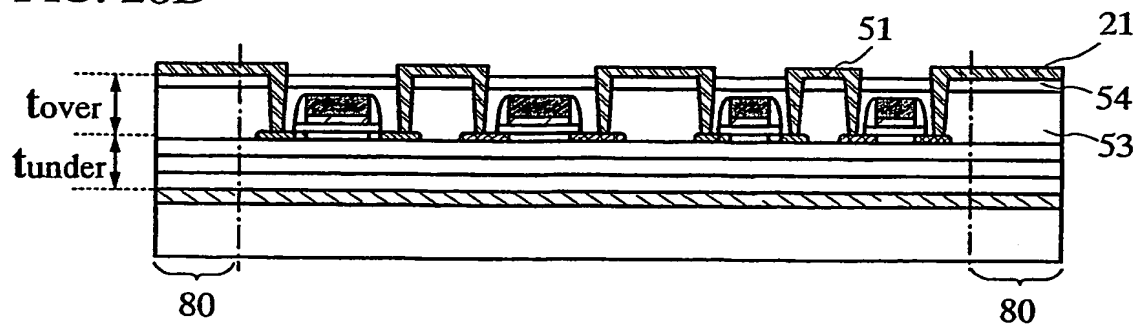


FIG. 20D



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FIG. 21A

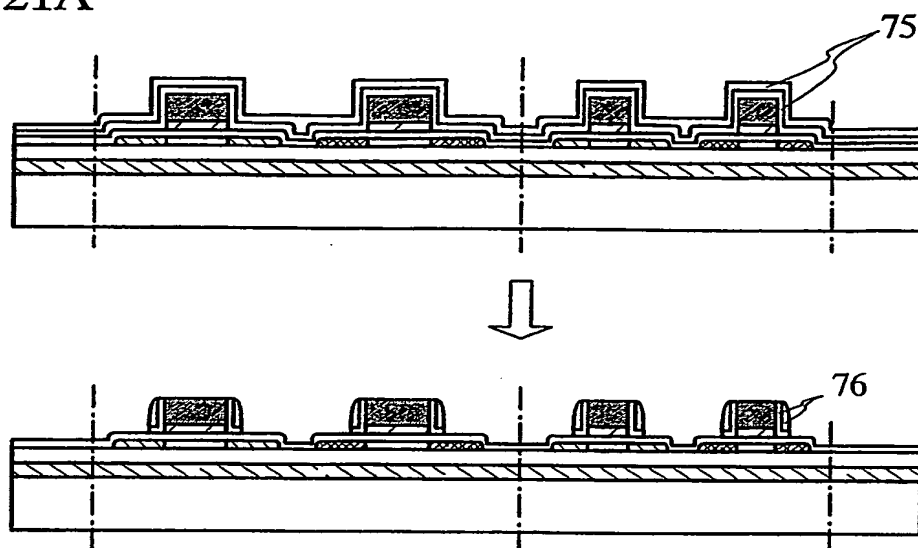
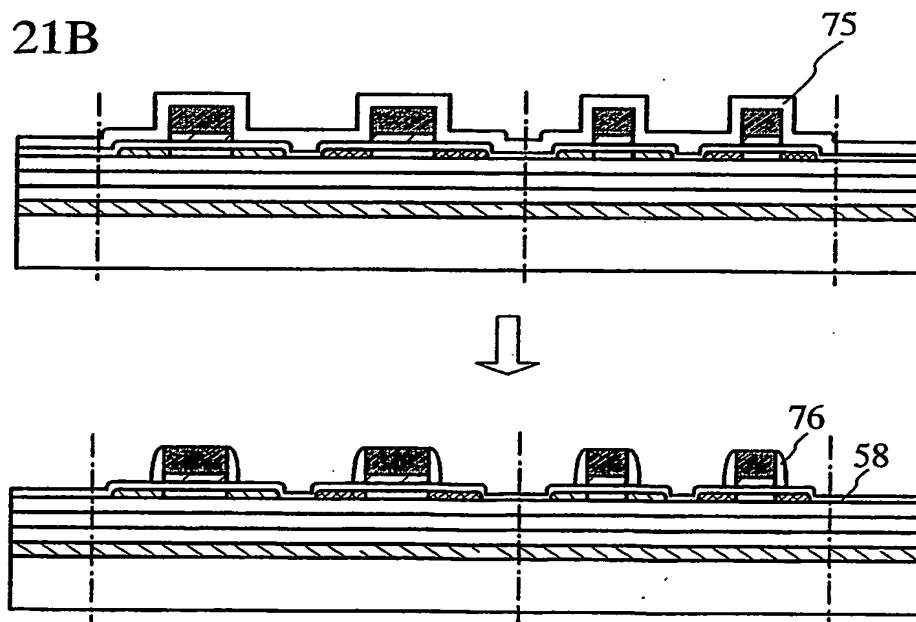


FIG. 21B



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FIG. 22



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FIG. 23A

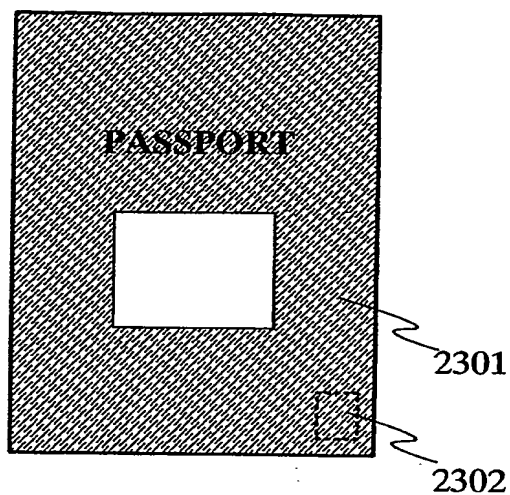


FIG. 23B

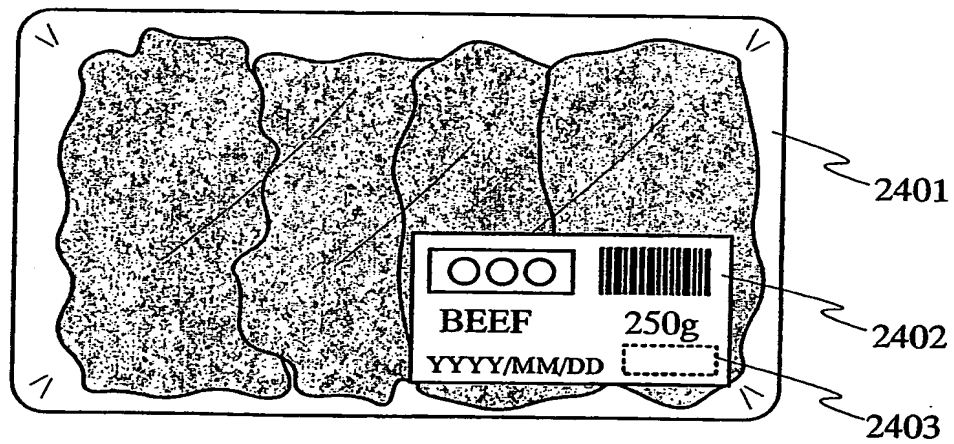
A rounded rectangular form with the following fields and layout:

- Name**: Two groups of two circles (representing letters) followed by the text "YYYY/MM/DD".
- Birth**: Six circles (representing digits).
- Address**: Six circles (representing digits) followed by the text "YYYY/MM/DD".
- Number**: Six circles (representing digits).
- Others**: A line for additional information.
- Photo Area**: A large rectangular area on the right side of the form.
- Signature Area**: A dashed rectangular area at the bottom right of the form.

Reference numeral 2303 points to the right side of the form, and 2304 points to the bottom right corner.

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FIG. 24



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FIG. 25A

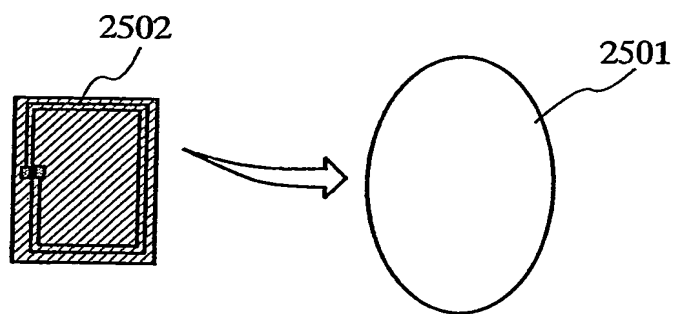
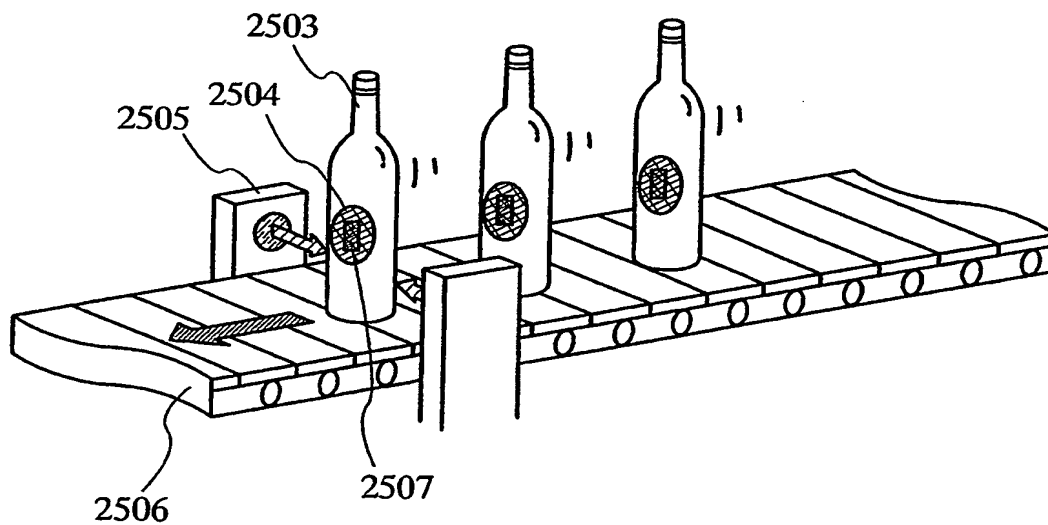
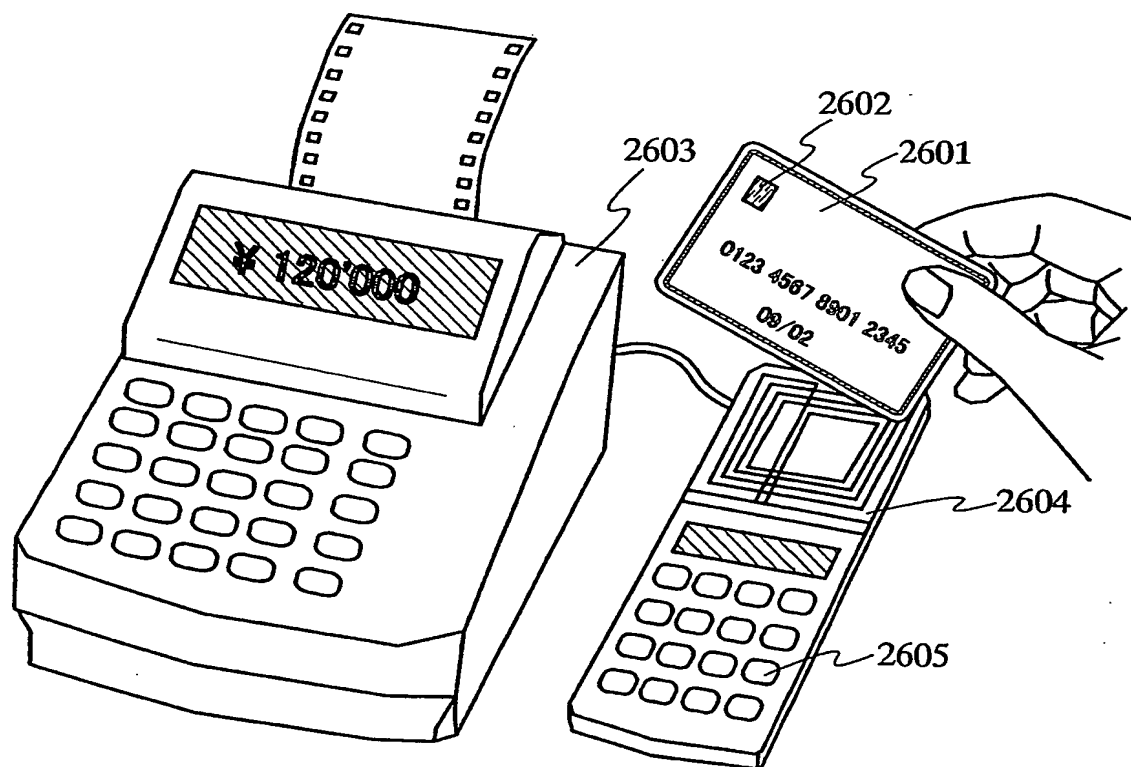


FIG. 25B



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FIG. 26



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EXPLANATION OF REFERENCE

1. power supply 2. power supply 21. connecting wiring 51. wiring 53.
interlayer film 54. protective film 55. protective film 56. gate electrode 57.
5 island shape semiconductor film 58. gate insulating film 60. substrate 61. peeling
layer 62. resist 63. resist 64. impurity element 65. low concentration impurity
region 66. resist 67. impurity element 68. high concentration impurity region 69.
N-channel TFT 70. P-channel TFT 71. N-channel TFT 72. P-channel TFT 73.
CPU 74. memory 75. insulating film 76. side wall 77. resist 78. impurity
10 element 79. high concentration impurity region 80. terminal portion 200.
semiconductor device 201. antenna circuit 202. rectification circuit 203.
stabilizing power supply circuit 205. modulation circuit 206. amplifier 207. logic
circuit 208. amplifier 209. logic circuit 211. memory circuit 212. memory
control circuit 213. demodulation circuit 301. antenna coil 302. tuning capacitor
15 303. diode 304. diode 305. smoothing capacitor 401. ID chip 402. antenna unit
403. interrogator 404. bag 501. concave mirror 502. convex mirror 503. reticle
504. substrate 505. slit 506. light source 601. stage 602. substrate 603. optical
system 604. reticle 605. optical system 606. slit 607. optical system 608. light
source 701. column decoder 702. row decoder 703. TFT 704. TFT 705. TFT
20 706. TFT 707. word line 708. word line 709. bit line (data line) 710. bit line
(data line) 711. column switch 712. column switch 713. power supply line 714.
load resistor 715. amplifier 716. output terminal 717. output wiring 718.
memory cell 719. memory cell 720. memory cell 721. memory cell 801. contact
hole 802. contact hole 803. contact hole 804. contact hole 1000. substrate
25 1001. antenna 1002. circuit 1003. substrate 1004. antenna 1005. circuit 1006.
substrate 1007. antenna 1008. circuit 1009. substrate 1010. antenna 1011.
circuit 1012. substrate 1013. antenna 1014. circuit 1100. substrate (upper
substrate) 1101. antenna (antenna wiring) 1600. IC card 1601. circuit portion

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1610. ID tag 1611. circuit portion 1620. product 1621. protective film 1622. ID
chip 1630. housing 1631. ID chip 1640. shipping tag 1641. ID chip 1650.
book 1651. protective film 1652. ID chip 1660. bill 1661. ID chip 1670. shoe
1671. protective film 1672. ID chip 1801. protective film 1802. ID chip 1803.
5 protective film 1804. antenna 2201. bag 2202. ID chip 2301. passport 2302.
ID chip 2303. driving license 2304. ID chip 2401. pack 2402. label 2403. ID
chip 2501. label 2502. ID chip 2503. beer bottle 2504. label 2505. writer
device 2506. conveyor belt 2507. ID chip 2601. IC card 2602. ID chip 2603.
cash register 2604. reader/writer 2605. key 3000. insulating substrate 3001.
10 base film 3002. base film 3003. island shape semiconductor layer 3004. island
shape semiconductor layer 3005. island shape semiconductor layer 3006. gate
insulating film 3007. conductive layer 3008. conductive layer 3009. conductive
layer 3011. conductive layer 3012. conductive layer 3013. conductive layer
3016. impurity region 3017. impurity region 3018. impurity region 3019.
15 impurity region 3020. side wall 3021. side wall 3022. impurity region 3023.
impurity region 3024. interlayer insulating film 3025. interlayer insulating film
3026. electrode 3027. electrode 3028. electrode 3029. electrode 3030. electrode
3031. contact 3032. contact 3033. contact 4000. peeling layer 4001. interlayer
insulating film 4002. pad 4003. pad 4004. pad 4005. pad 4006. protective
20 film 4007. groove 4008. adhesive 4009. support base